

LOW CAPACITANCE FLIP CHIP ARRAY

APPLICATIONS

- ✓ Cellular Phones
- ✓ Personal Digital Assistant (PDA)
- ✓ Notebook Computers
- ✓ SMART Cards

IEC COMPATIBILITY (EN61000-4)

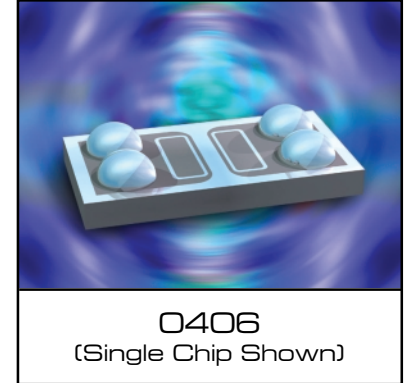
- ✓ 61000-4-2 (ESD): Air - 15kV, Contact - 8kV
- ✓ 61000-4-4 (EFT): 40A - 5/50ns

FEATURES

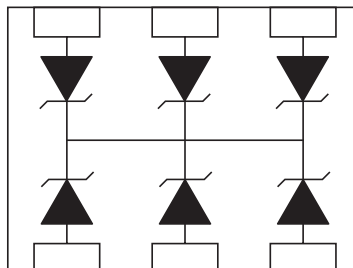
- ✓ ESD Protection > 25 kilovolts
- ✓ Available in Six Voltage Types Ranging From 3.3V to 24V
- ✓ 200 Watts Peak Pulse Power per Line ($t_p = 8/20\mu s$)
- ✓ Low Clamping Voltage
- ✓ Bidirectional Configuration & Monolithic Structure
- ✓ Protects 3 to 5 Lines
- ✓ **LOW CAPACITANCE**
- ✓ **LOW LEAKAGE CURRENT**

MECHANICAL CHARACTERISTICS

- ✓ Standard EIA Chip Size: 0406
- ✓ Weight 0.73 milligrams (Approximate)
- ✓ Flammability Rating UL 94V-0
- ✓ 8mm Plastic & Paper Tape and Reel Per EIA Standard 481
- ✓ Device Marking On Reel
- ✓ Top Contacts: Solder Bump 0.004" in Height (Nominal)



PIN CONFIGURATION



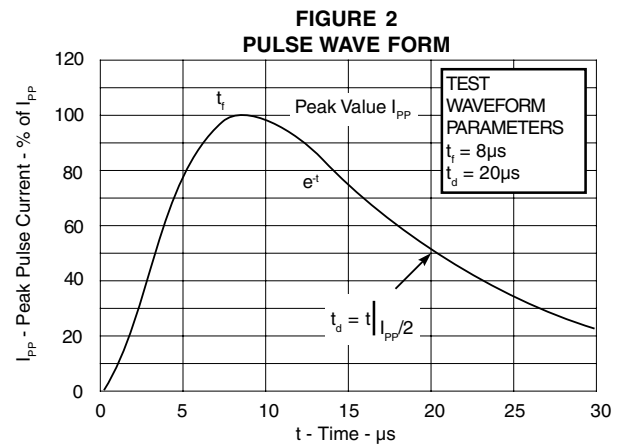
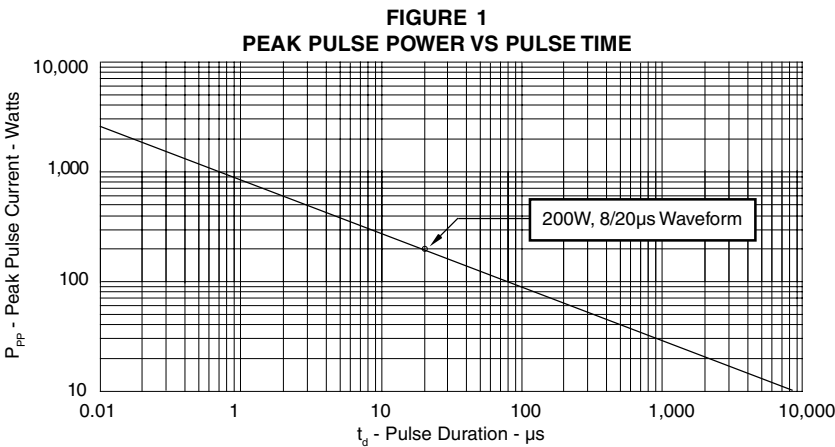
DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power ($t_p = 8/20\mu s$) - See Figure 1	P_{PP}	200	Watts
Operating Temperature	T_J	-55°C to 150°C	°C
Storage Temperature	T_{STG}	-55°C to 150°C	°C

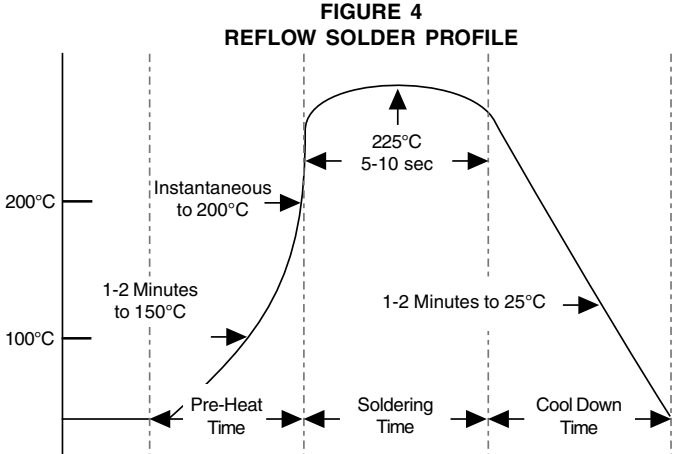
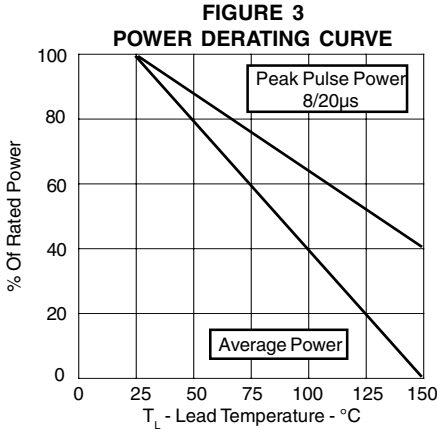
ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified						
PART NUMBER (See Note 1)	RATED STAND-OFF VOLTAGE V_{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA $V_{(BR)}$ VOLTS	MAXIMUM CLAMPING VOLTAGE (See Fig. 2) @ $I_p = 1A$ V_C VOLTS	MAXIMUM CLAMPING VOLTAGE (See Fig. 2) @ 8/20 μs $V_C @ I_{PP}$	MAXIMUM LEAKAGE CURRENT (See Note 2) @ V_{WM} I_D μA	TYPICAL CAPACITANCE
						@ 0V, 1 MHz C pF
LC0406FC3.3C	3.3	4.0	7.0	12.5V @ 16A	75*	70
LC0406FC05C	5.9	6.0	11.0	13V @ 15A	10**	35
LC0406FC08C	8.0	8.5	13.2	18V @ 11A	1	32
LC0406FC12C	12.0	13.3	19.8	26.9V @ 7.4A	1	30
LC0406FC15C	15.0	16.7	25.4	34.5V @ 5.8A	1	25
LC0406FC24C	24.0	26.7	37.2	50.6V @ 4A	1	20

Note 1: All devices are bidirectional. Electrical characteristics apply in both directions.

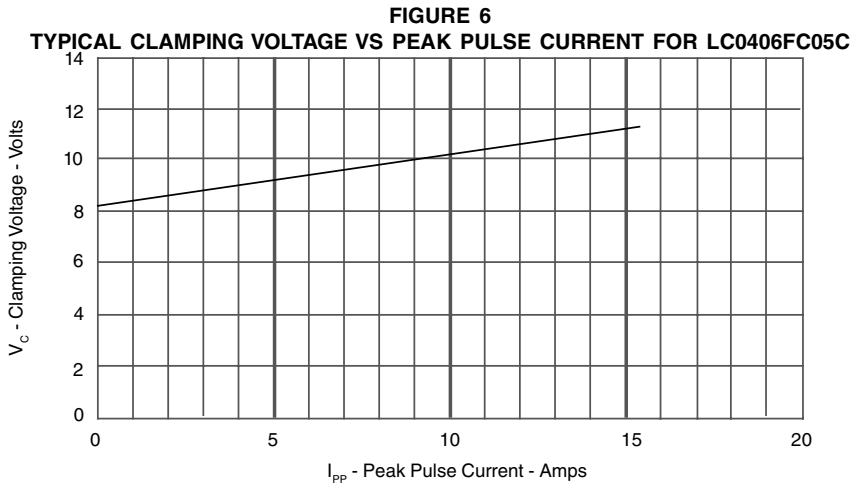
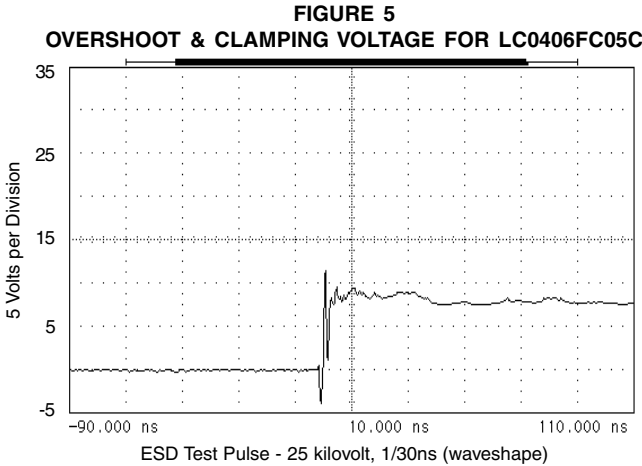
Note 2: *Maximum leakage current < 5 μA @ 2.8V. **Maximum leakage current < 500nA @ 3.3V.



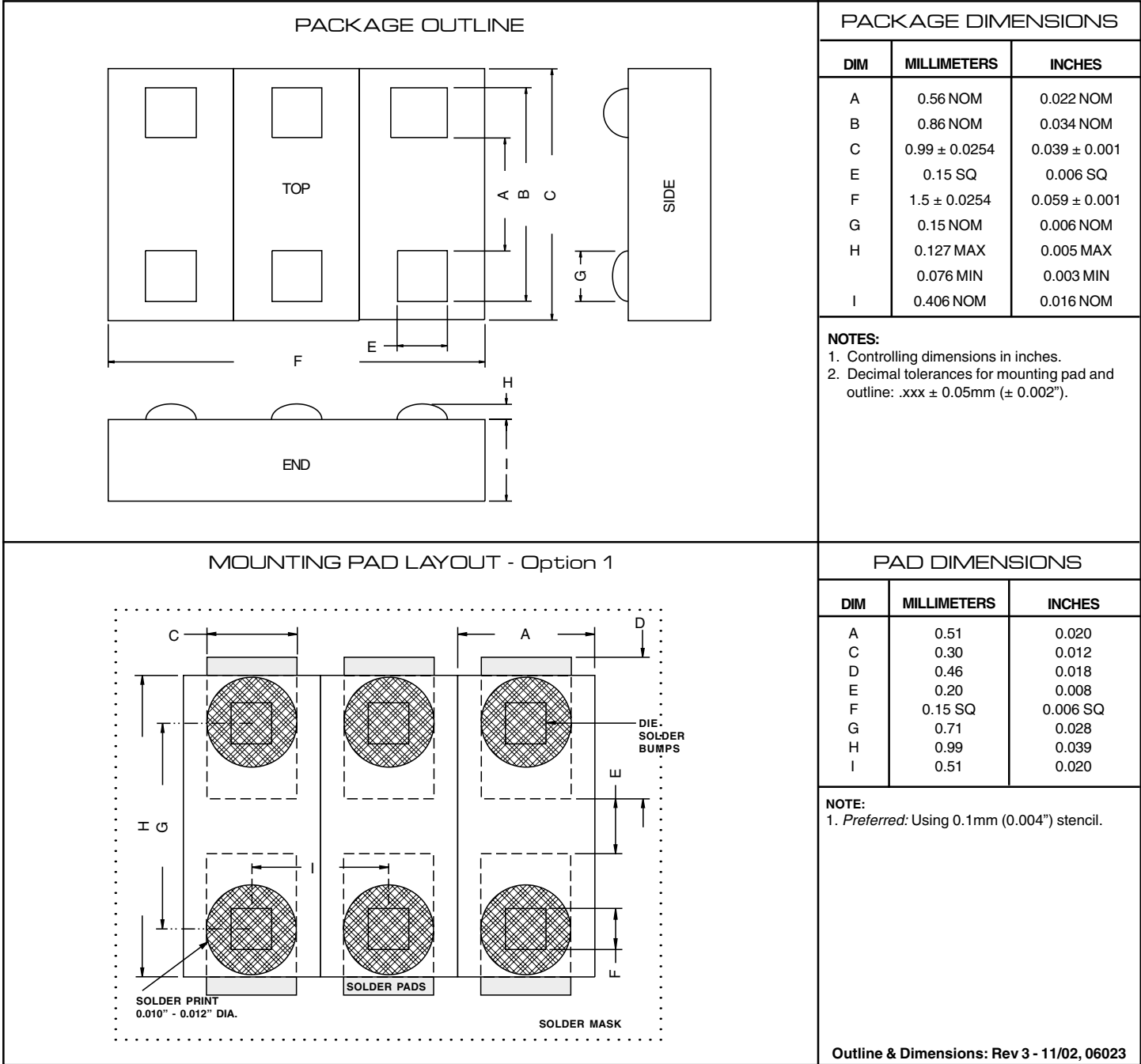
GRAPHS



Note: This reflow profile does not take into account the printed circuit board (PCB) material heating time. Additional time may be required for the preheat time and cool down time upon the PCB or board material.



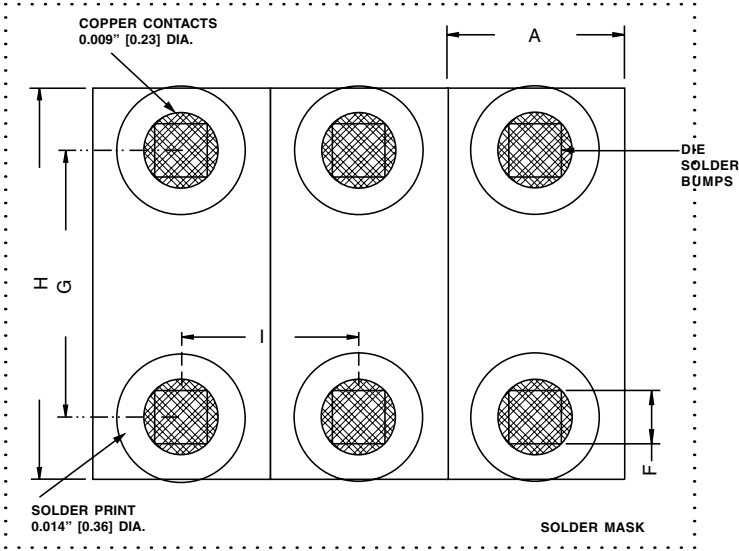
PACKAGE OUTLINE & DIMENSIONS



LC0406FC3.3C thru LC0406FC24C

PACKAGE OUTLINE & DIMENSIONS

MOUNTING PAD LAYOUT - Option 2



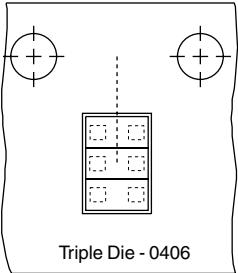
PACKAGE DIMENSIONS

DIM	MILLIMETERS	INCHES
A	0.51	0.020
F	0.15 SQ	0.006 SQ
G	0.71	0.028
H	0.99	0.039
I	0.51	0.020

- NOTES:**
1. Controlling dimensions in inches.
 2. Decimal tolerances for mounting pad and outline: .xxx ± 0.05mm (± 0.002").
 3. Preferred: Using 0.1mm (0.004") stencil.

Outline & Dimensions: Rev 3 - 11/02, 06023

TAPE & REEL ORIENTATION



- NOTE:**
1. Top view of tape. Solder bumps are face down in tape package.

TAPE & REEL ORDERING NOMENCLATURE

1. Surface mount product is taped and reeled in accordance with EIA 481.
2. 8mm Plastic Tape: 7 Inch Reels - 5,000 pieces per reel. Ordering Suffix: -T75-1 (i.e., LC0406FC05C-T75-1).
3. 8mm Paper Tape: 7 Inch Reels - 5,000 pieces per reel. Ordering Suffix: -T75-2 (i.e., LC0406FC05C-T75-2).

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